

# VUSB002R52APA

**Datasheet** 





### 520mΩ, -20V, P-Channel Power MOSFET

### VUSB002R52APA

### **General Description**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)_max</sub>	$I_D$
	520mΩ@-4.5V	
-20V	780mΩ@-2.5V	-0.66A
	1100mΩ@-1.8V	

# **Symbol**

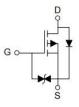


Figure 1 Symbol of VUSB002R52APA

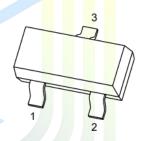
### **Features**

- Trench Technology Power MOSFET
- Low R<sub>DS(ON)</sub>
- Low Gate Charge
- ESD Protected

# **Application**

- Load Switching
- Low Current Inverters
- Low Current DC/DC Converters

# Package Type



- 1. GATE
- 2. SOURCE
- 3. DRAIN

SOT-23

Figure 2 Package Type of VUSB002R52APA

### **Ordering Information**

Product Name	Package		
VUSB002R52APA	SOT-23		



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# Absolute Maximum Ratings (T<sub>A</sub>= 25 °C, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DSS</sub>	-20	V
Gate-Source Voltage	V <sub>GSS</sub>	±12	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	-0.66	Δ.
Pulsed Drain Current Note2	$I_{DM}$	-2.0	A
Total Power Dissipation <sup>Note4</sup>	P <sub>D</sub>	0.35	W
Junction Temperature	$T_{\rm J}$	150	°C
Storage Temperature	T <sub>STG</sub>	-55 to 150	°C

### **Thermal Resistance**

Parameter Parame	Symbol	<mark>M</mark> in	Typ	Max	Unit	
Thermal Resistance, Junction-to-Ambient <sup>Note5</sup>	R <sub>0JA</sub>		3 <mark>57</mark>		°C/W	





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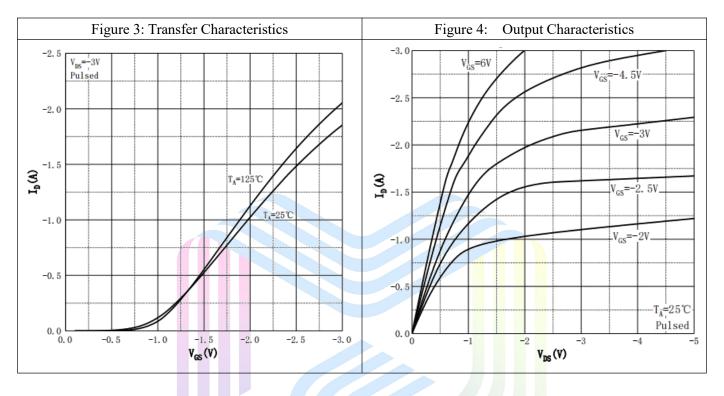
### Electrical Characteristics (T<sub>J</sub>= 25 °C, unless otherwise specified)

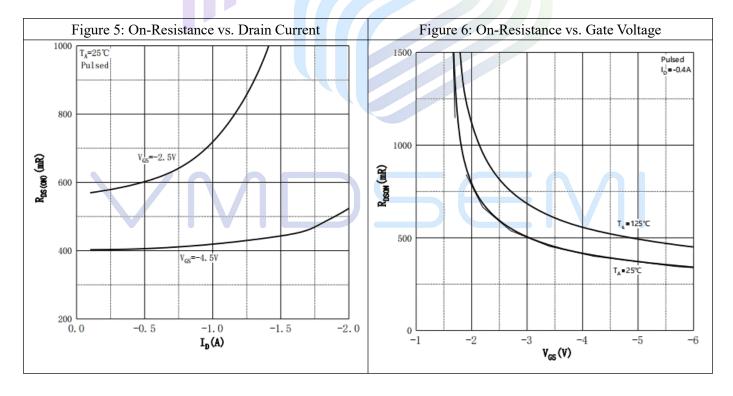
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250uA$ -20				V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -16V, V_{GS} = 0V$			-1	uA
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 10V, V_{DS} = 0V$			±10	uA
Gate Threshold Voltage <sup>Note3</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=-250uA$	-0.4	-0.7	-1.0	V
		$V_{GS}$ =-4.5V, $I_D$ = -0.5A		400	520	
Static Drain-Source On-Resistance <sup>Note3</sup>	R <sub>DS(ON)</sub>	$V_{GS}$ =-2.5V, $I_D$ = -0.3A		570	780	m $\Omega$
		$V_{GS}$ =-1.8V, $I_D$ = -0.12A		810	1100	
Forward Transconductance <sup>Note3</sup>	g <sub>FS</sub>	$V_{DS}$ =-5V, $I_{D}$ = -0.4A		1		S
Dynamic Characteristics						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =-10V		79		pF
Output Capacitance	Coss	V <sub>GS</sub> =0V		15		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>	f=1MHz		13		pF
Total Gate Charge	Qg	V <sub>DS</sub> =-10V		2.26		
Gate-Source Charge	$Q_{\mathrm{gs}}$	V <sub>GS</sub> =-4.5V		0.45		nC
Gate-Drain Charge	Qgd	$I_D = -0.2A$		0.24		
Gate Resistance	Rg	f = 1MHz, Open drain		5		Ω
Switching Parameters						
Turn-on Delay Time	t <sub>d(on)</sub>	$V_{DD} = -10V$		8		
Turn-on Rise Time	t <sub>r</sub>	$V_{GS} = -4.5V$		5.5		
Turn-off Delay Time	$t_{ m d(off)}$	$R_L=50\Omega$		30		ns
Turn-off Fall Time	$t_{\mathrm{f}}$	$R_G=3\Omega$		17		
Diode Characteristics						
Diode Forward Voltage Note3	$V_{\mathrm{SD}}$	$V_{GS}=0V, I_{S}=-0.5A$			-1.2	V

#### Notes:

- 1. The maximum current rating is limited by package. And device mounted on a large heatsink.
- 2. Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3. Pulse Test : Pulse Width  $\leq 300 \mu s$ , duty cycle  $\leq 2\%$ .
- 4. The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^{\circ}C$ . And device mounted on a large heatsink
- 5.Device mounted on  $1\text{in}^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A$  =25°C.

# **Typical Performance Characteristics**

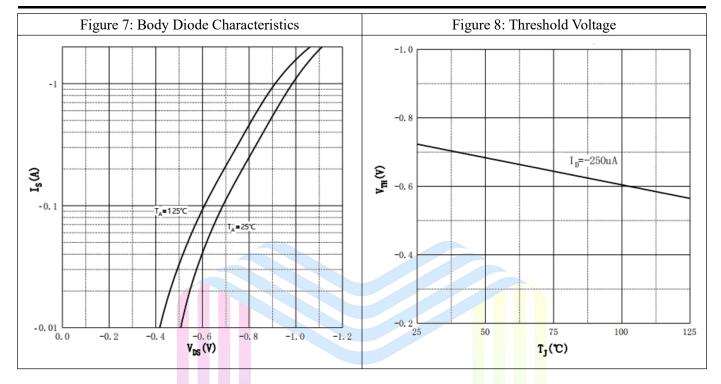






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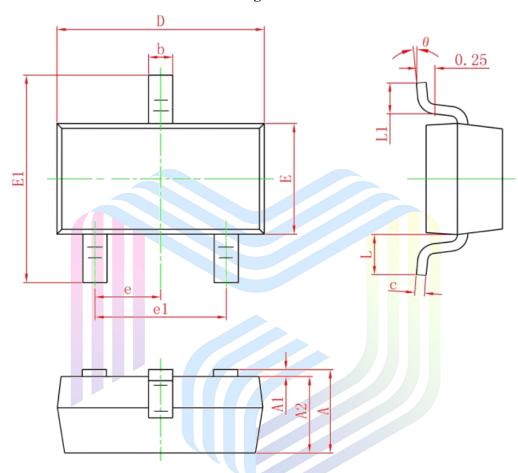




# $520m\Omega$ , -20V, P-Channel Power MOSFET

# **Mechanical Dimensions:**

**SOT-23 Package Information** 



Cumbal	Dimensions In Millimeters		Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
A	0.900	1.150	0.035	0.045		
A1	0	0.100	0	0.004		
A2	0.900	1.050	0.035	0.041		
b	0.300	0.500	0.012	0.020		
С	0.080	0.150	0.003	0.006		
D	2.800	3.000	0.110	0.118		
E	1.150	1.500	0.045	0.059		
E1	2.250	2.650	0.089	0.104		
е	0.950TYP		e 0.950TYP		0.037	TYP
e1	1.800	2.000	0.071	0.079		
L	0.550REF		L 0.550REF 0.02		0.022	REF
L1	0.300	0.500	0.012	0.020		
θ	0°	8°	0°	8°		

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